



Joint

Web Seminar

5G Alliance for Connected Industries and Automation



Invitation

Joint Web Seminar on Industrial 5G with OPC UA
June 22nd 2022, Online via WebEx

Interoperable Industrial 5G and OPC UA in the Shopfloor - an absolute prerequisite for Industry 4.0

The fourth stage of the industrial revolution heralds an entirely new era. Its goal is to significantly improve the flexibility, versatility, usability and efficiency of production systems and to make the vision of smart factories come true.

In this context, the integration of OPC UA and Industrial 5G, two important building blocks are brought together, thus forming the basis for a highly flexible and powerful connectivity fabric for smart manufacturing.

Learn in our breakout sessions more from the experts on how both technologies will revolutionize the shopfloor.

The entire joint web seminar is free of charge.
We look forward to meeting you!

For questions, please contact:

5G Alliance for Connected Industries and Automation

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OPC Foundation

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Agenda | European Morning Session

Date: June 22nd 2022

Time: 9:00–11:00 CEST (16:00–18:00 JST)

<i>Time (CEST)</i>	<i>Topic</i>	<i>Speaker</i>
09:00–09:10	Opening	Dr. Afif Osseiran / Moderation (5G-ACIA General Vice-Chair, Ericsson) Dr. Andreas Mueller (5G-ACIA General Chair, Bosch) Stefan Hoppe (President OPC Foundation)
09:10–09:30	OPC UA and UAFX with Industrial Use Cases and 5G	Peter Lutz (Director FLC, OPC Foundation) Alexander Ziegler (Siemens)
09:30–09:50	5G Architecture and Integration with Industrial Networks	Atte Lansisalmi (5G-AICA WG3 Vice-Chair, Nokia)
09:50–10:10	Recent Development on OPC UA with 5G	Xueli An (5G-ACIA WG1 Vice-Chair, Huawei)
10:10–10:35	Live Demonstration/ OPC UA over 5G	Peter Lutz (Director FLC, OPC Foundation) Josef Eichinger (5G-ACIA Board Member, Huawei) Alexander Ziegler (Siemens)
10:35–10:55	Panel Discussion with Q&A	Peter Lutz (Director FLC, OPC Foundation) Atte Lansisalmi (5G-AICA WG3 Vice-Chair, Nokia) Josef Eichinger (5G-ACIA Board Member, Huawei)
10:55–11:00	Closure of the Session and Outlook	Dr. Afif Osseiran / Moderation (5G-ACIA General Vice-Chair, Ericsson)



Please register online for the **morning session** [here](#).



Agenda | European Evening Session

Date: June 22nd 2022

Time: 15:00-17:00 CEST (08:00-10:00 CDT)

<i>Time (CEST)</i>	<i>Topic</i>	<i>Speaker</i>
15:00-15:10	Opening	Peter Lutz (Director FLC, OPC Foundation) Dr. Andreas Mueller (5G-ACIA General Chair, Bosch) Stefan Hoppe (President OPC Foundation)
15:10-15:30	OPC UA and UAFX with Industrial Use Cases and 5G	Peter Lutz (Director FLC, OPC Foundation) Alexander Ziegler (Siemens)
15:30-15:50	5G Architecture and integration with industrial networks	Kurt Essigmann (5G-AICA WG3 Chair, Ericsson)
15:50-16:10	Recent Development on OPC UA with 5G	Xueli An (5G-ACIA WG1 Vice-Chair, Huawei)
16:10-16:35	Live Demonstration/ OPC UA over 5G	Peter Lutz (Director FLC, OPC Foundation) Josef Eichinger (5G-ACIA Board Member, Huawei) Alexander Ziegler (Siemens)
16:35-16:55	Panel Discussion with Q&A	Peter Lutz (Director FLC, OPC Foundation) Kurt Essigmann (5G-AICA WG3 Chair, Ericsson) Josef Eichinger (5G-ACIA Board Member, Huawei)
16:55-17:00	Closure of the Session and Outlook	Peter Lutz (Director FLC, OPC Foundation)



Please register online for the **evening session** [here](#).

We look forward to meeting you!

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